

# MPW Shuttle Service 2009

a leap ahead

## Schedule

Process	Data and Order to	Tape In	Samples Out <sup>6)</sup>
<b>0.18 µm HV-CMOS 50V <sup>8)</sup></b>			
H18	austria <i>micro systems</i>	20-Apr-09	13-Jul-09
H18	austria <i>micro systems</i>	20-Jul-09	12-Oct-09
H18	austria <i>micro systems</i>	16-Nov-09	08-Feb-10
<b>0.18 µm CMOS 1.8V / 2.5V / 3.3V (5V <sup>7)</sup>)</b>			
C18	austria <i>micro systems</i>	02-Feb-09	27-Apr-09
C18	austria <i>micro systems</i>	25-May-09	17-Aug-09
C18	austria <i>micro systems</i>	03-Aug-09	27-Oct-09
C18	austria <i>micro systems</i>	23-Nov-09	15-Feb-10
<b>0.35 µm HV-CMOS 20V/50V/120V (embedded Flash <sup>5)</sup>)</b>			
H35B4D3	austria <i>micro systems</i>	09-Feb-09	10-Apr-09
H35B4D3	austria <i>micro systems</i>	11-May-09	10-Jul-09
H35B4D3	austria <i>micro systems</i>	17-Aug-09	16-Oct-09
H35B4D3	austria <i>micro systems</i>	09-Nov-09	08-Jan-10
<b>0.35 µm CMOS 3.3V / 5V (embedded Flash <sup>5)</sup>) and 0.35 µm Opto-CMOS <sup>2)</sup></b>			
C35 <sup>1)</sup>	austria <i>micro systems</i>	02-Feb-09	20-Mar-09
C35 <sup>1)</sup>	austria <i>micro systems</i>	16-Mar-09	30-Apr-09
C35 <sup>1) 2)</sup>	Fraunhofer IIS	27-Apr-09	17-Jun-09
C35 <sup>1)</sup>	austria <i>micro systems</i>	08-Jun-09	24-Jul-09
C35 <sup>1)</sup>	austria <i>micro systems</i>	27-Jul-09	11-Sep-09
C35 <sup>1)</sup>	austria <i>micro systems</i>	21-Sep-09	06-Nov-09
C35 <sup>1) 2)</sup>	Fraunhofer IIS	26-Oct-09	15-Dec-09
C35 <sup>1)</sup>	austria <i>micro systems</i>	14-Dec-09	29-Jan-10
<b>0.35 µm SiGe-BiCMOS 3.3V / 5V 2P/4M</b>			
S35	austria <i>micro systems</i>	09-Mar-09	08-May-09
S35	austria <i>micro systems</i>	15-Jun-09	14-Aug-09
S35	austria <i>micro systems</i>	14-Sep-09	13-Nov-09
S35	austria <i>micro systems</i>	30-Nov-09	29-Jan-10
<b>Additional MPW Shuttles are scheduled by our partners</b>			
<b>Fraunhofer IIS</b> <a href="http://www.iis.fraunhofer.de">www.iis.fraunhofer.de</a>		 <b>Europractice</b> <a href="http://www.europractice-ic.com">www.europractice-ic.com</a>	
<b>CMP</b> <a href="http://cmp.imag.fr">cmp.imag.fr</a>		 <b>MOSIS</b> <a href="http://www.mosis.com">www.mosis.com</a>	
<b>CONTACTS:</b>			
austria <i>micro systems</i> <a href="mailto:sigurd.hellinger@austriamicrosystems.com">mailto:sigurd.hellinger@austriamicrosystems.com</a>		<b>Fraunhofer IIS</b> <a href="mailto:virtual-asic@iis.fraunhofer.de">mailto:virtual-asic@iis.fraunhofer.de</a>	

## Price List

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Process Family	Unit Price in EURO / mm <sup>2</sup>	Minimum Charge in EURO	Comment
0.35 µm CMOS	810 <sup>4)</sup>	9,850 <sup>4)</sup>	
0.35 µm Opto-CMOS	1,010 <sup>4)</sup>	14,500 <sup>4)</sup>	
0.35 µm SiGe-BiCMOS	1,220 <sup>4)</sup>	9,850 <sup>4)</sup>	
0.35 µm HV-CMOS	1,140 <sup>4)</sup>	9,850 <sup>4)</sup>	
0.18 µm HV-CMOS	price on request	price on request	
0.18 µm CMOS	price on request	price on request	
0.35 µm CMOS embedded Flash <sup>5)</sup>	price on request	price on request	
0.35 µm HV-CMOS embedded Flash <sup>5)</sup>	price on request	price on request	

### Standard Services

The participation on the austria *micro systems* MPW service includes the delivery of 30 dice.

**Option:** Double placement of a chip on the MPW cluster duplicates unit prices respectively minimum charges and maximum number of available dice or assembled parts.

**Note:** Process stops, wafer probe tests or wafer shipments are not possible for MPWs.

### Additional Services

Additional Services	Unit Price in EURO	Comment
Additional Dice	<b>Quotation required!</b>	Up to 100 possible from single placement on MPW.
10 parts in ceramic package with taped lid	1,000 per lot	Min. 1 lot
10 parts in scoop&goop package <sup>3)</sup>	1,000 per lot	Min. 1 lot
50 parts in plastic package up to 84 pins	2,500 per lot	Max. 2 lots (100 pcs). Larger qty. through multiple placement on MPW.

### Notes

<sup>1)</sup> Represents different process options (exception: RF-CMOS, e.g. C35B4M3), designs with 3 metal layers will be processed as separate lot split.

<sup>2)</sup> Opto option available on request. Opto CMOS process only available for 2 poly / 4 metal.

<sup>3)</sup> Availability check necessary at tape in.

<sup>4)</sup> This price list is only valid for MPW starts at austria *micro systems*.

<sup>5)</sup> EEPROM option available on request, quotation required. Licence fee for Flash block not included.

<sup>6)</sup> The Sample Out dates are without obligation. The total cycle time includes MPW cluster preparation, wafer back-lapping, dicing, assembling in ceramic or the scoop&goop package. For plastic assembly an additional cycle time of 3 weeks has to be calculated.

<sup>7)</sup> Available process options C18

**Important note:** The Addendum Document has to be submitted at tape out!

<sup>8)</sup> Available process options H18

**Important note:** The Addendum Document has to be submitted 2 weeks in advance to tape out!

### Disclaimer

**No implied offer:** The usage of austriamicrosystems design kits and/or libraries or the participation on Multi Project Wafer runs shall not be regarded as an implied offer by austriamicrosystems to subsequently manufacture such integrated circuit. In any case each integrated circuit, which is planned for production, requires an official quotation by austriamicrosystems.

### Technical Information

Technical web: [asic.austriamicrosystems.com](http://asic.austriamicrosystems.com)  
Tape-out form: [Foundry Request Form](#)  
Form for 0.18 µm: [Addendum Document](#)

For orders in US \$ exchange rate to be quoted.  
Delivery dates are subject to change without notice.

**WE RESERVE THE RIGHTS TO MAKE CHANGES WITHOUT NOTICE!**  
Purchase orders are based on austria *micro systems* General Terms of Trade.